TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSV)

TPC8012-H

Switching Regulator Application DC-DC Converters

• Low drain-source ON resistance: RDS (ON) = 0.28Ω (typ.)

• High forward transfer admittance: $|Y_{fs}| = 1.35 \text{ S (typ.)}$

• Low leakage current: $I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 200 \text{ V)}$

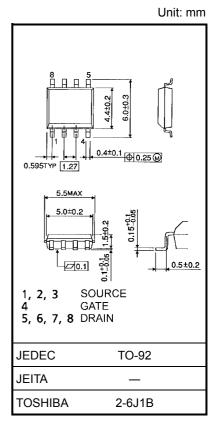
• Enhancement mode: $V_{th} = 3.0 \text{ to } 5.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

Maximum Ratings (Ta = 25°C)

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	200	V	
Drain-gate voltage (R	k _{GS} = 20 kΩ)	V_{DGR}	200	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	1.8	Α	
Diam current	Pulse (Note 1)	I_{DP}	7.2	^	
Drain power dissipati	on $(t = 10 s)$ (Note 2a)	P_{D}	1.9	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	P _D	1.0	W	
Single pulse avalanch	ne energy (Note 3)	E _{AS}	2.05	mJ	
Avalanche current		I _{AR}	1.8	Α	
Repetitive avalanche	energy Note 2a) (Note 4)	E _{AR}	0.19	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature	range	T _{stg}	-55 to 150	°C	

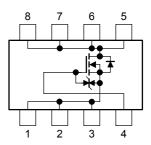
Note: (Note 1), (Note 2), (Note 3), (Note 4) Please see next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.80 g (typ.)

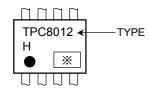
Circuit Configuration



Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th (ch-a)}	65.8	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	125	°C/W

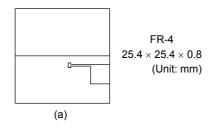
Marking (Note 5)

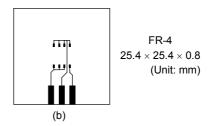


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)





Note 3: V_{DD} = 50 V, T_{ch} = 25°C (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = 1.8 A

Note 4: Repetitive rating; pulse width limited by maximum channel temperature

Note 5: • on lower left of the marking indicates Pin 1.

* shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively.)

Electrical Characteristics (Ta = 25°C)

Cha	Characteristics		Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cut-OFF cu	rrent	I _{DSS}	V _{DS} = 200 V, V _{GS} = 0 V		_	100	μА
Drain-source brea	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	200	200 — —		V
Gate threshold vo	<u> </u>		$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$	3.0	_	5.0	V
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 10 V, I _D = 0.9 A	_	0.28	0.40	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 0.9 A	0.65 1.35 —		_	S
Input capacitance		C _{iss}		_	440	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		80	_	
Output capacitance		C _{oss}			260	_	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	Rise time	t _r	10 V □ lp = 0.9 A	_	23	_	
	_						
Switching time	Fall time	ton V _{GS} 10 V I _D = 0.9 A C C S C C S C C C C C C C C C C C C C	ns				
	Turn-OFF time	t _{off}	V _{DD} ≃ 100 V	_	73	_	
		Qg			11		nC
Gate-source charge 1		Q _{gs1}			6		
Gate-drain ("miller") charge		Q _{gd}			5		

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Drain reverse current	Pulse	(Note 1)	I _{DRP}	_	_	_	7.2	Α
Forward voltage (diode)			V_{DSF}	$I_{DR} = 1.8 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.5	V

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